

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of: Basceri et al.  
Application No. 09/965,509

Filed: September 26, 2001

For: METHODS FOR FORMING AND  
INTEGRATED CIRCUIT STRUCTURES  
CONTAINING ENHANCED-SURFACE-AREA  
CONDUCTIVE LAYERS

Examiner: Toniae M. Thomas

Date: March 3, 2003

COMMISSIONER FOR PATENTS  
WASHINGTON, D.C. 20231

Art Unit: 2812

CERTIFICATE OF MAILING

I hereby certify that this paper and the documents referred to as being attached or enclosed herewith are being deposited with the United States Postal Service on March 3, 2003 as First Class Mail in an envelope addressed to: COMMISSIONER FOR PATENTS, WASHINGTON, D.C. 20231.

*Mar 6 2003*  
Attorney for Applicant

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7/B And  
3-17-03  
A.Walk

**AMENDMENT**

In response to the Office action of December 3, 2002, please amend the subject application as follows:

In the claims:

Please amend claims 30, 31, and 42 as follows:

30. (Amended) An enhanced-surface-area conductive structure in an integrated circuit, the structure comprising:  
a supporting structure;  
a conductive layer situated on a surface of the supporting structure; and  
a layer of ruthenium oxide having at least one pitted surface situated on the conductive layer.

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